

## **AMENDMENTS TO THE SPECIFICATION:**

Please replace paragraph No. 0006 ( on page 2), with the following rewritten paragraph:

1 [0006] The chip according to an embodiment of the invention is of  
2 particularly simple construction that makes possible a cost-effective production  
3 process, consisting of only a few process steps, which is of particular importance  
4 when mass products, such as smart labels, are to be manufactured. The cover  
5 plate fulfils a dual function in this case. It allows the encapsulation of the chip  
6 and, at the same time, the establishment of electrical contact between the chip  
7 and the conductive layer that may consist, for example, of a transponder aerial.  
8 The chip is also mechanically stress-relieved in that the conductive layer is at  
9 least as high as the chip, or higher than the chip. This fact is particularly useful  
10 when the chip is integrated in a smart label.